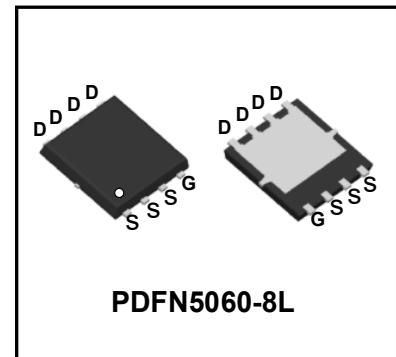


# WMB017N03LG2

## 30V N-Channel Enhancement Mode Power MOSFET

### Description

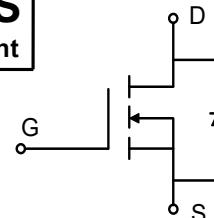
WMB017N03LG2 uses Wayon's 2<sup>nd</sup> generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.



PDFN5060-8L

### Features

- $V_{DS} = 30V$ ,  $I_D = 100A$   
 $R_{DS(on)} < 1.7m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(on)} < 2.5m\Omega$  @  $V_{GS} = 4.5V$
- Low  $R_{DS(on)}$
- Low Gate Charge
- 100% EAS Guaranteed
- RoHS and Halogen-Free Compliant



### Applications

- Power Management in Switches
- DC/DC Converter

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source voltage	$V_{DS}$	30	V
Gate-Source voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current  $T_C=25^\circ C$	$I_D$	100	A
$T_C=100^\circ C$		63.3	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	400	A
Single Pulse Avalanche Energy <sup>2</sup>	$EAS$	45	mJ
Total Power Dissipation  $T_C=25^\circ C$	$P_D$	30.5	W
Operating Junction and Storage Temperature Range	$T_J$ , $T_{STG}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	53	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	4.1	$^\circ C/W$

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30	-	-	V
Gate-body Leakage Current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$I_{\text{DSS}}$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	$\mu\text{A}$
			-	-	100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.2	1.6	2.2	V
Drain-Source On-Resistance <sup>4</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	-	1.3	1.7	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 20\text{A}$	-	1.9	2.5	
Forward Transconductance <sup>4</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 5\text{V}, I_D = 20\text{A}$	-	36	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	3480	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	1800	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	225	-	
Gate Resistance	$R_G$	$f = 1\text{MHz}$	-	0.7	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 15\text{V}, I_D = 20\text{A}$	-	46	-	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		-	9.9	-	
Gate-Drain Charge	$Q_{\text{gd}}$		-	6.5	-	
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 15\text{V}, R_G = 3.3\Omega, I_D = 20\text{A}$	-	10.5	-	$\text{ns}$
Rise Time	$t_r$		-	6.2	-	
Turn-off Delay Time	$t_{\text{d(off)}}$		-	55	-	
Fall Time	$t_f$		-	8.5	-	
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	38.8	-	$\text{ns}$
Reverse Recovery Charge	$Q_{\text{rr}}$		-	30	-	$\text{nC}$
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{\text{SD}}$	$I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V
Continuous Source Current	$T_C = 25^\circ\text{C}$	$I_S$	-	-	100	A

## Notes:

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})} = 150^\circ\text{C}$
2. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}} = 25\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.1\text{mH}, I_{\text{AS}} = 30\text{A}$
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

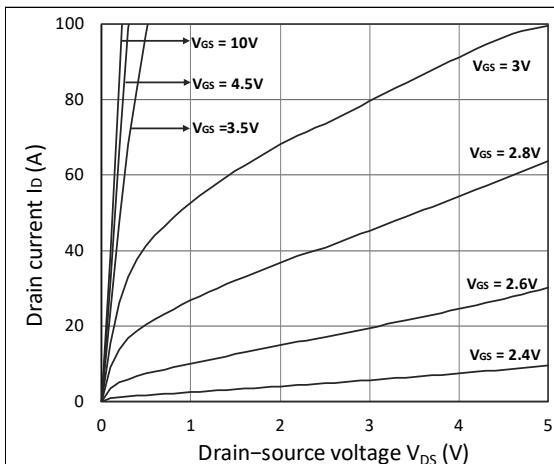


Figure 1. Output Characteristics

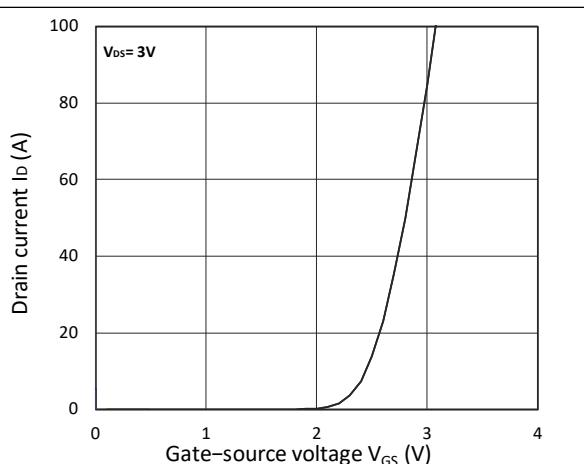


Figure 2. Transfer Characteristics

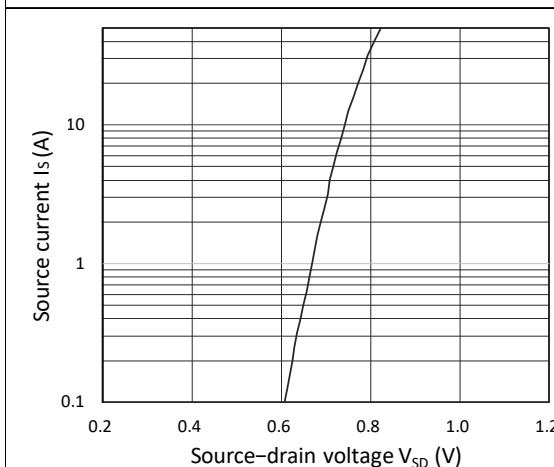
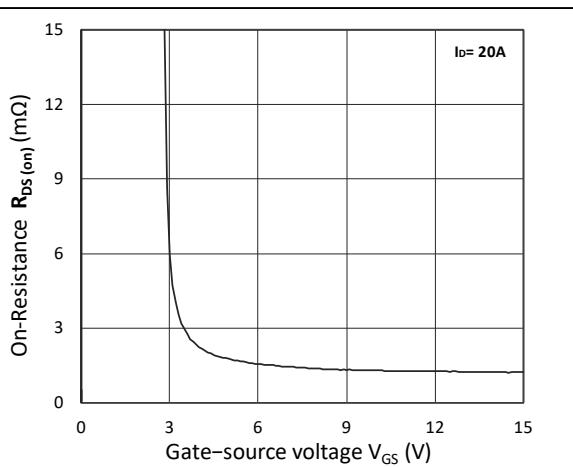
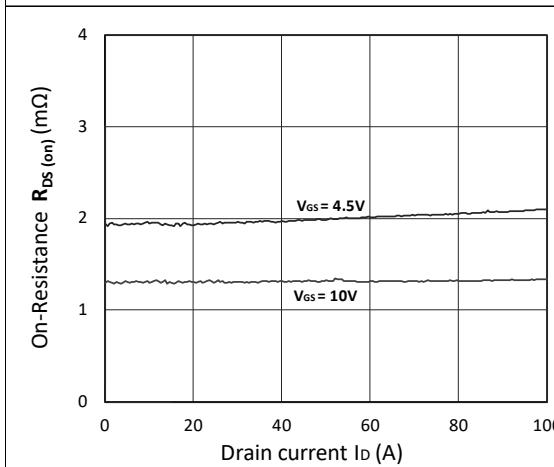
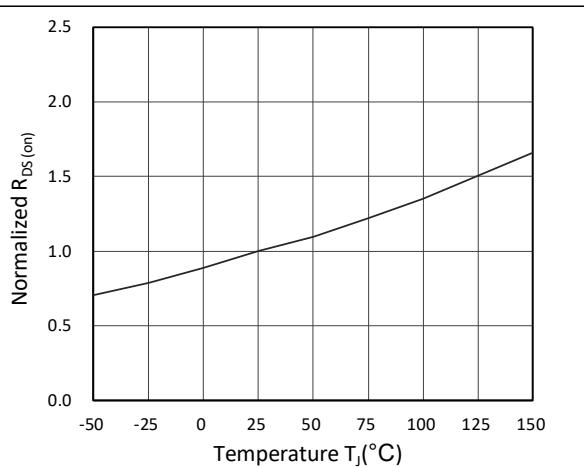


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

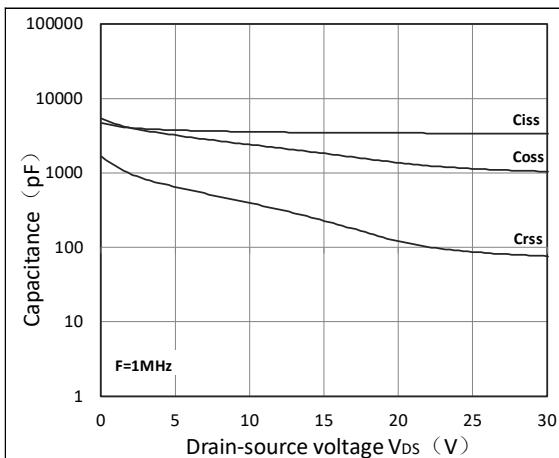


Figure 7. Capacitance Characteristics

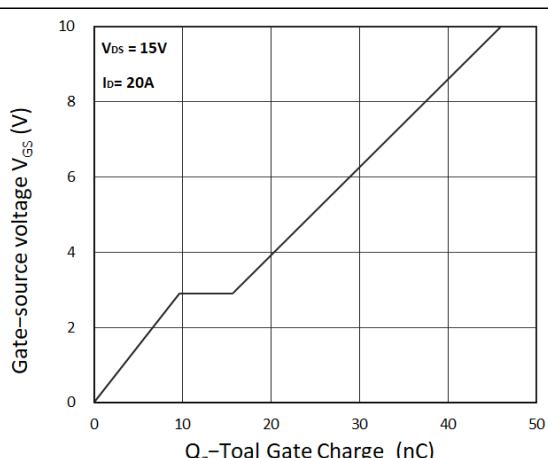


Figure 8. Gate Charge Characteristics

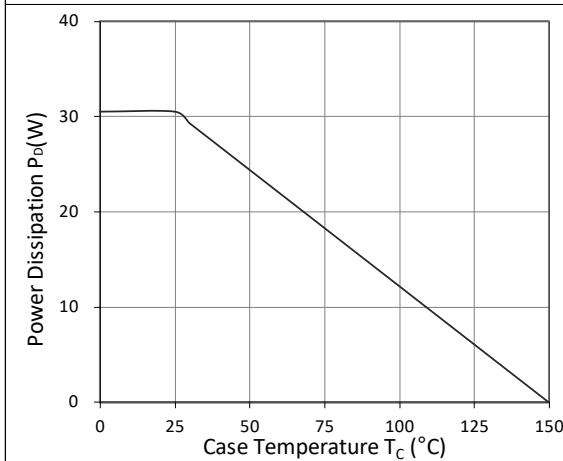


Figure 9. Power Dissipation

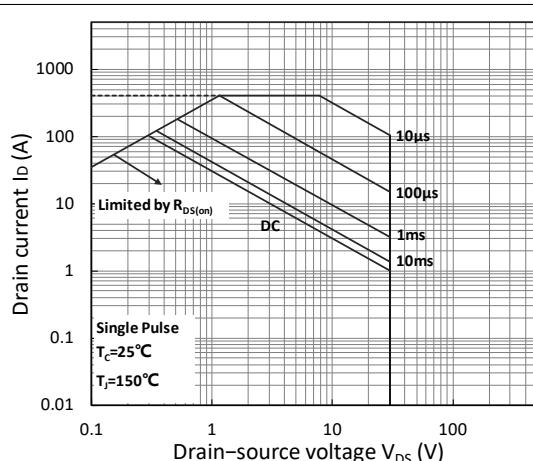


Figure 10. Safe Operating Area

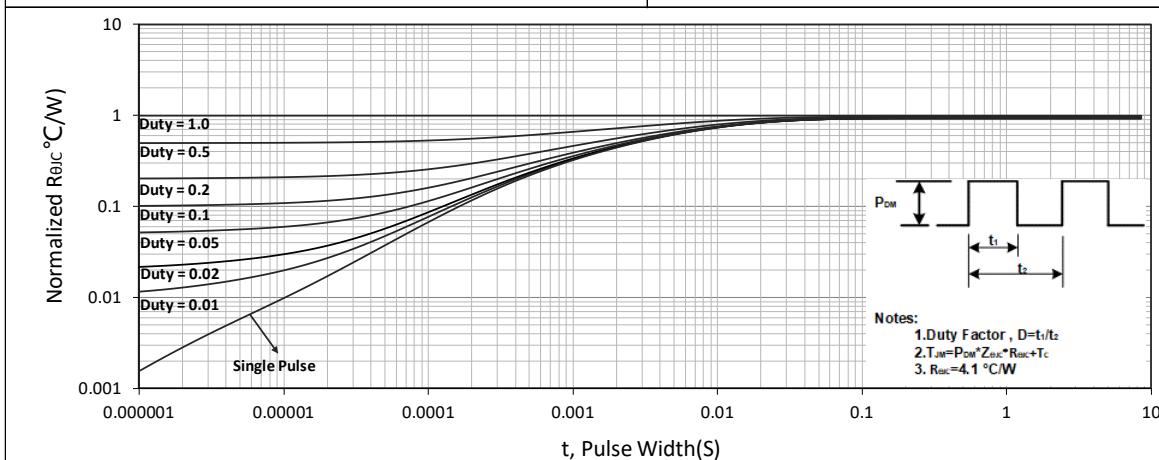
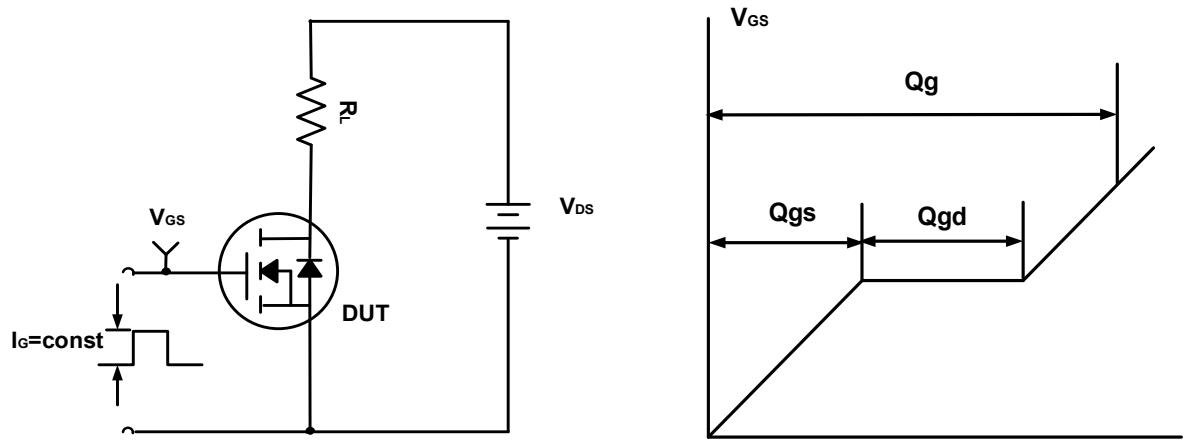
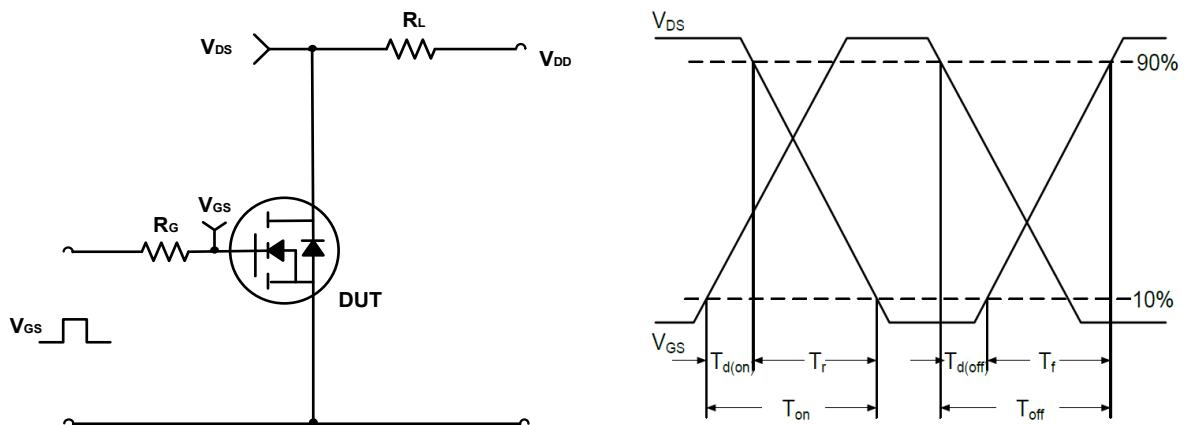
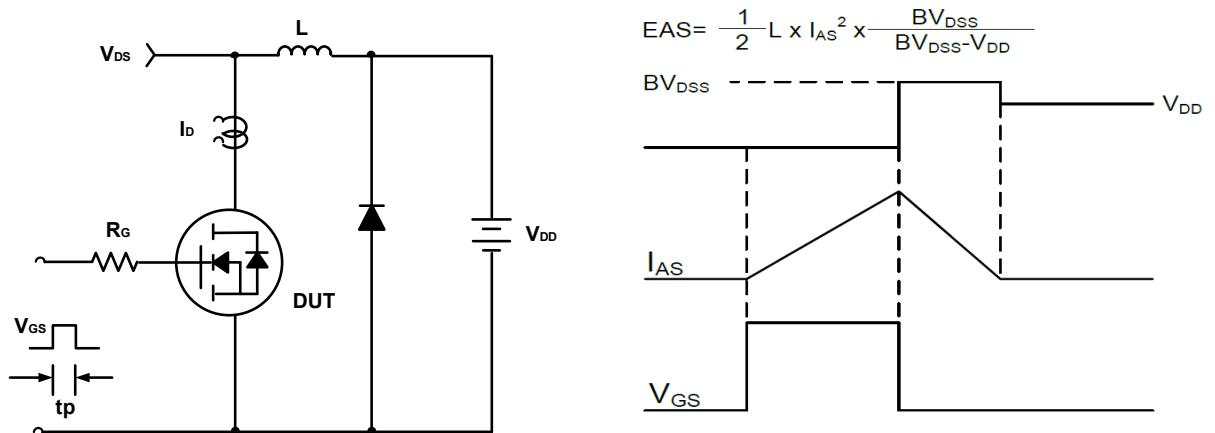
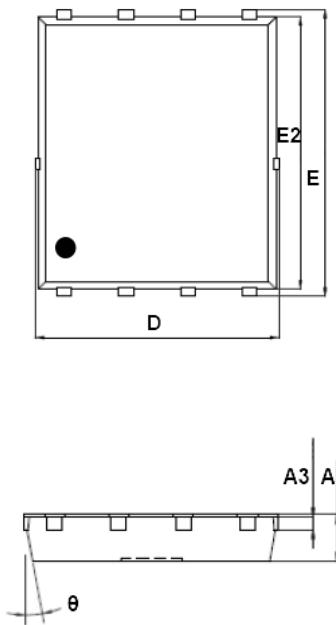


Figure 11. Normalized Maximum Transient Thermal Impedance

**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Mechanical Dimensions for PDFN5060-8L

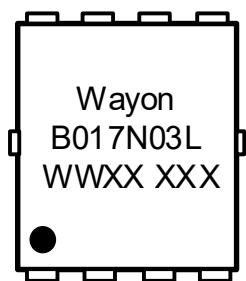
## COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	0.90	1.20
A3	0.15	0.35
D	4.80	5.40
E	5.90	6.35
D1	3.61	4.31
E1	3.30	3.92
E2	5.50	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.71
θ	0°	12°

**Ordering Information**

Part	Package	Marking	Packing method
WMB017N03LG2	PDFN5060-8L	B017N03L	Tape and Reel

**Marking Information**

B017N03L = Device code

WWXX XXX= Date code